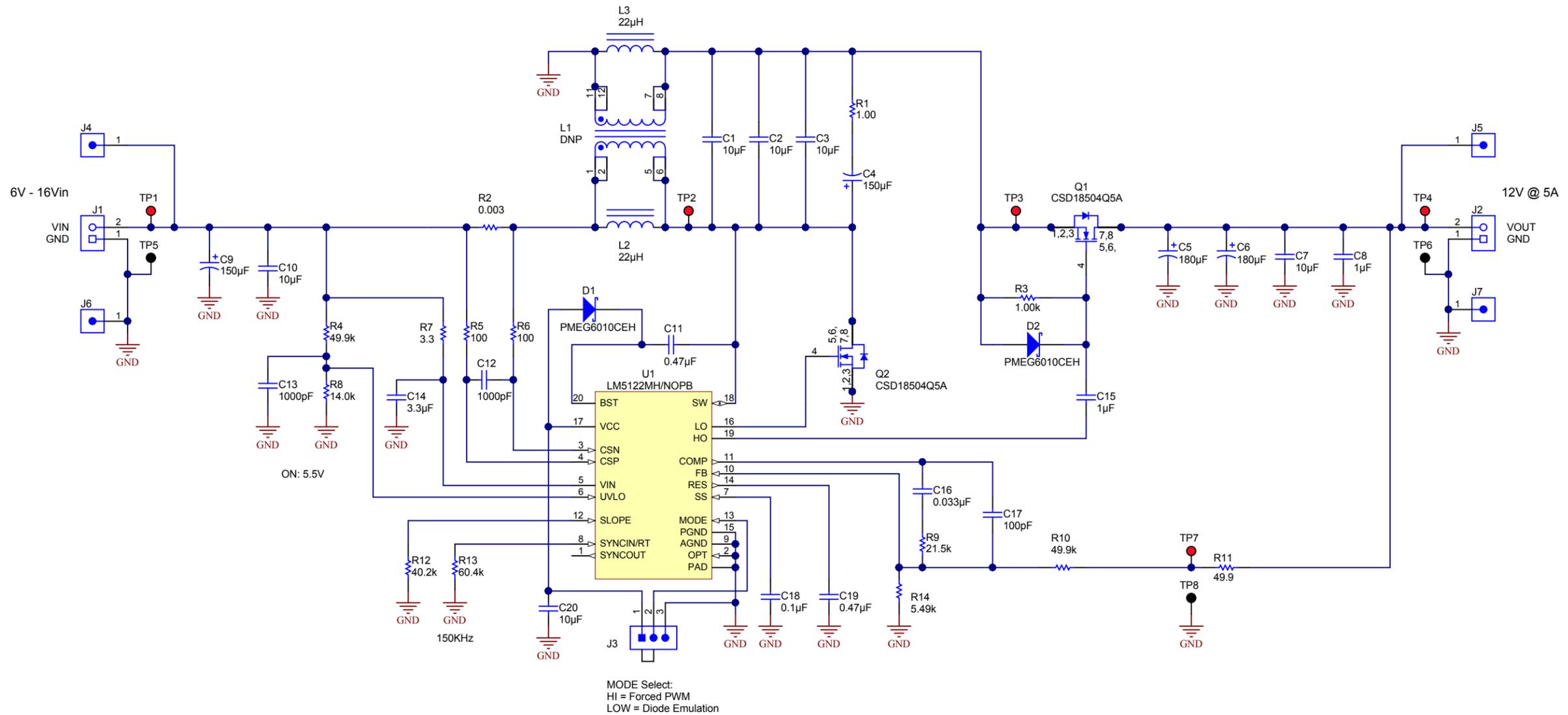


Separate Inductor Version:  
DO NOT INSTALL  
L1

Coupled Inductor Version:  
DO NOT INSTALL  
L2, L3, R1, C4



MODE Select:  
HI = Forced PWM  
LOW = Diode Emulation

H1  
ELDE 0553\_10

H2  
ELDE 0553\_10

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Orderable: N/A	Designed for: Public Release	Mod. Date: 1/30/2015
TID #:	Project Title: LM5122 Sync SEPIC	
Number: PMP10886	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 1
Drawn By:	File: PMP10886 REVA.SchDoc	Size: B
Engineer: J Betten	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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